

10-02-2002

FORM PTO-1595 (Modified)  
(Rev. 03-01)  
OMB No. 0651-0027 (exp. 5/31/2002)  
P08A/REV03



HEET

U.S. DEPARTMENT OF COMMERCE  
Patent and Trademark Office

102239327

Tab settings

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

William L. Brodsky  
William E. Buchler, Jr.  
Benson Chan

Additional names(s) of conveying party(ies)  Yes  No

2. Name and address of receiving party(ies):

Name: International Business Machines Corporation

Address: New Orchard Road

City: Armonk State/Prov.: NY

Country: US ZIP: 10504

Additional name(s) & address(es)  Yes  No

3. Nature of conveyance:

9.25-02

- Assignment  Merger
- Security Agreement  Change of Name
- Other

Execution Date: 9/24/02

4. Application number(s) or patent numbers(s):

10/254239

If this document is being filed together with a new application, the execution date of the application is: 9/24/02

Patent Application No. Filing date

B. Patent No.(s)

10/01/2002 6TOM11 00000069 090457 10254239

01 FC:581 40.00 CH

Additional numbers

Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Ronald A. D'Alessandro

Registration No. 42,456

Address: Hoffman, Warnick & D'Alessandro LLC

Three E-Comm Square

City: Albany State/Prov.: NY

Country: US ZIP: 12207

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

- Enclosed - Any excess or insufficiency should be credited or debited to deposit account
- Authorized to be charged to deposit account

8. Deposit account number:

09-0457 (IBM)

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Lawrence R. Fraley - Reg. No. 26,885

Name of Person Signing

*Lawrence R. Fraley*  
Signature

Sept. 25, 2002  
Date

3

Total number of pages including cover sheet, attachments, and

**ASSIGNMENT**

Whereas we,

(1) William L. Brodsky  
County of Broome

City of Binghamton  
and State of New York, US

(2) William E. Buchler, Jr.  
County of Tioga

City of Owego  
and State of New York , US

and

(3) Benson Chan  
County of Broome

City of Vestal  
and State of New York , US

**have invented certain improvements in**

**LAND GRID ARRAY CONNECTOR AND METHOD FOR FORMING THE SAME**

and have executed, respectively, a United States patent application therefor on

- (1) 9/24, 2002;
- (2) 9/24, 2002; and
- (3) 9/24, 2002.

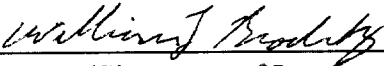
**Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;**

**Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we the above named hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.**

---

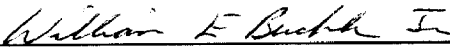
**LAND GRID ARRAY CONNECTOR AND METHOD FOR FORMING THE SAME**

Signed at Endicott, NY  
on 9/24/2002

  
(Signature of Inventor)

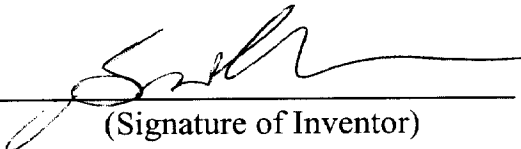
William L. Brodsky  
(Typed Name of Inventor)

Signed at ENDICOTT NY  
on 9-24-02

  
(Signature of Inventor)

William E. Buchler, Jr.  
(Typed Name of Inventor)

Signed at Endicott NY  
on 9/24/02

  
(Signature of Inventor)

Benson Chan  
(Typed Name of Inventor)